

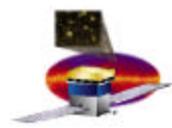
GLAST Large Area Telescope Calorimeter Subsystem

4.0 Calorimeter Design and Development

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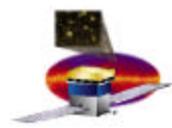




Outline

- ❑ **Design and Development**
 - **Science Requirements and Performance**
 - **Calorimeter Concept**
 - **Design Evolution**
 - **LAT Calorimeter Design**
 - **EM Calorimeter**
 - **Status and Performance**
 - **FM Testing and Calibration**



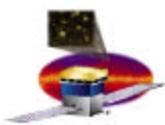


Level III Science Requirements

□ Requirements that bear on science performance of CAL

Parameter	Requirement
Design	Modular, hodoscopic, CsI > 8.4 RL of CsI on axis
Active area	>1050 cm ² per module < 16% of total mass is passive material
Energy range	20 MeV – 300 GeV 5 MeV – 100 GeV (single crystal)
Energy resolution (1 sigma)	< 20% (20 MeV < E < 100 MeV) < 10% (100 MeV < E < 10 GeV) < 6% (10 GeV < E < 300 GeV, incidence angle > 60 deg)
Energy resolution (1 sigma) Single crystal	< 2% for Carbon ions of energy > 100 MeV/n, at a point
Position resolution	< 3 cm in 3 dims, minimum-ionizing particles, Incident angle < 45 deg
Angular resolution	15° x cos θ , for muons in 8 layers





Level III Requirements

❑ How do we know Level III requirements are met?

- Proof by design
- Proof by simulation
- Proof by demonstration
 - Prototype calorimeters
 - Engineering Model CAL

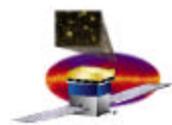
❑ Geometry requirements

- Proof by design

Parameter	Requirement
Design	Modular, hodoscopic, CsI > 8.4 RL of CsI on axis
Active area	>1050 cm ² per module < 16% of total mass is passive material

Performance
Modular, hodoscopic, CsI 8.6 RL of CsI on axis
1080 cm ² per module <14% passive material



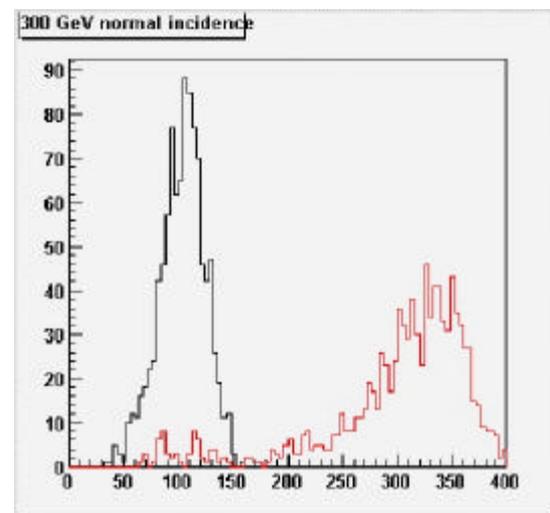
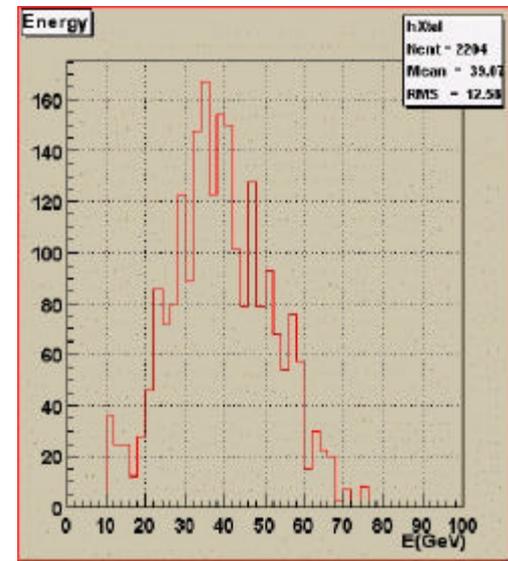


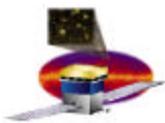
Level III: Energy Range

Parameter	Requirement
Energy range	20 MeV – 300 GeV (full CAL) 5 MeV – 100 GeV (single xtal)

- Proof by analysis/simulation and demonstration
 - Lower limit determined by electronic noise
 - Need to set zero-suppress threshold at 5 x noise
 - EM noise < 0.3 MeV → threshold < 2 MeV
 - Upper limit determined by
 - Saturation of electronics
 - EM saturates at ~100 GeV (single xtal)
 - Shower containment in CAL
 - CAL Monte Carlo simulation

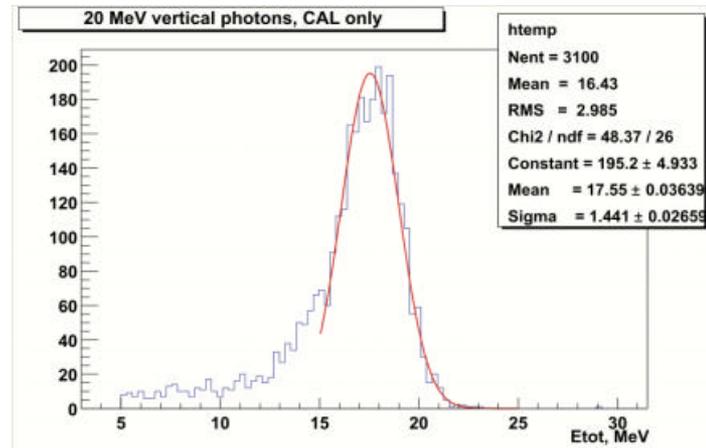
Expected Performance
20 MeV – 300 GeV (full CAL)
~2 MeV – 100 GeV (single xtal)





Level III: Energy resolution

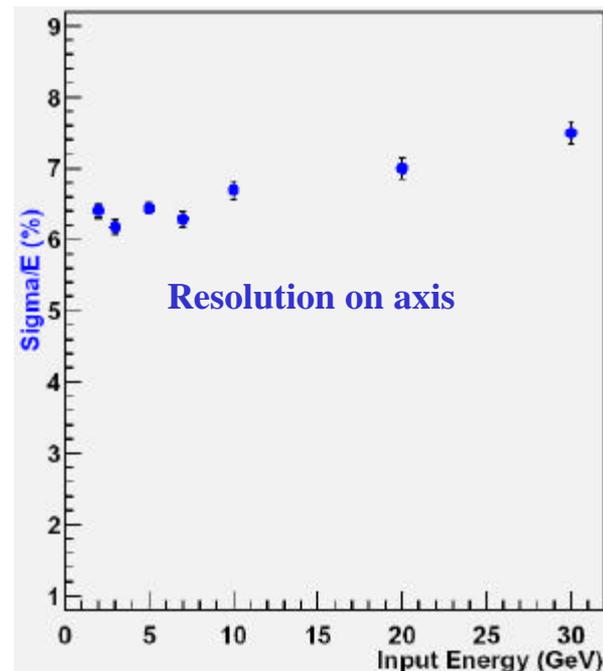
Parameter	Requirement
Energy resolution (1 sigma)	<p>< 20% (20 MeV < E < 100 MeV)</p> <p>< 10% (100 MeV < E < 10 GeV)</p> <p>< 6% (10 GeV < E < 300 GeV, >60°)</p>
Energy resolution (1 sigma) Single crystal	< 2% for Carbon ions of energy > 100 MeV/n, at a point

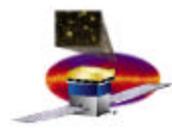


□ Proof by simulations, beam tests

- Below ~ 200 MeV, dominated by Tracker calorimetry
 - Required performance not yet demonstrated at 100 MeV: current best ~15%
- Above ~ 10 GeV, dominated by leakage

Expected Performance
< 8% (1 GeV < E < 10 GeV)
< 6% (10 GeV < E < 300 GeV, >60°)

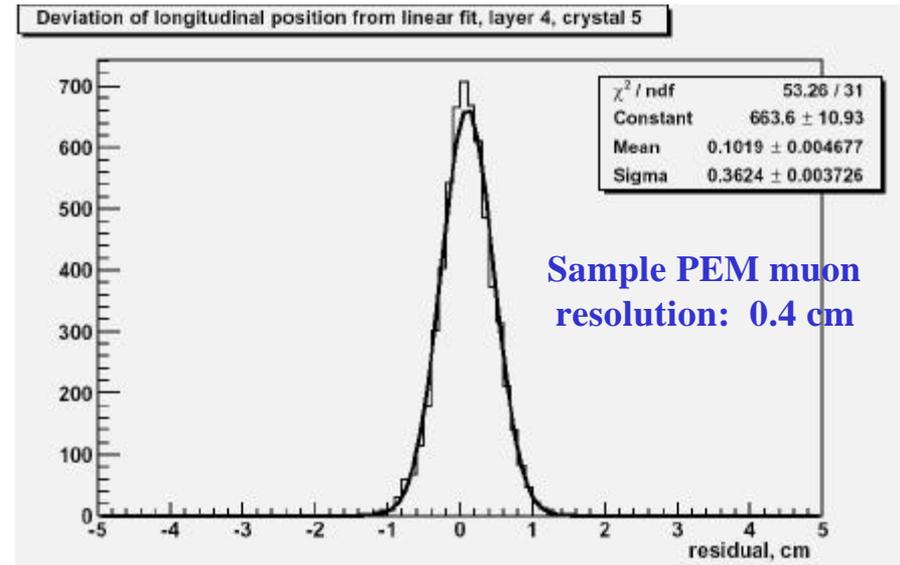


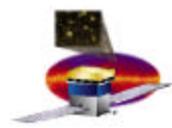


Level III: Position and Angular Resolution

Parameter	Requirement
Position res	< 3 cm in 3D, min-ionizing, < 45 deg
Angular res	$15^\circ \times \cos\theta$, for muons in 8 layers

- Proof by demonstration, simulation
 - Cross section of xtal
 - 1.99 cm x 2.67 cm
 - Longitudinal positioning
 - Defined by electronic noise
 - BTEM performance
 - ~3 cm
 - EM performance
 - Typical PEM rms < 0.5 cm
 - EM Module not yet demonstrated
 - Expect FM performance
 - 1.5 cm at 30 deg
 - Angular resolution
 - Calculated from positioning
 - EM performance not yet demonstrated
 - Expect FM performance
 - $8^\circ \times \cos\theta$



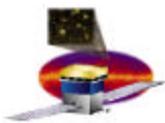


Calorimeter Concept

- ❑ **Calorimeter Concept, or, How we got there from here....**

- ❑ **LAT is modular**
 - **So CAL is modular**
- ❑ **Active CAL or Sampling CAL?**
 - **Low E performance rules out sampling**
 - **Maintain high stopping power for EM showers within the mass budget**
- ❑ **Imaging CAL**
 - **Energy-profile fitting improves energy resolution**
 - **Background rejection**
 - **CAL-only events**
- ❑ **Segmentation**
 - **Moliere radius is 38 mm**
 - **Radiation length is 19 mm**
 - **Bkg rejection requires positioning on same order**
 - **Xtals have cross section with dimension on this order**
 - **Xtals give longitudinal positions better than this order**





Energy Reconstruction

Shower profiling

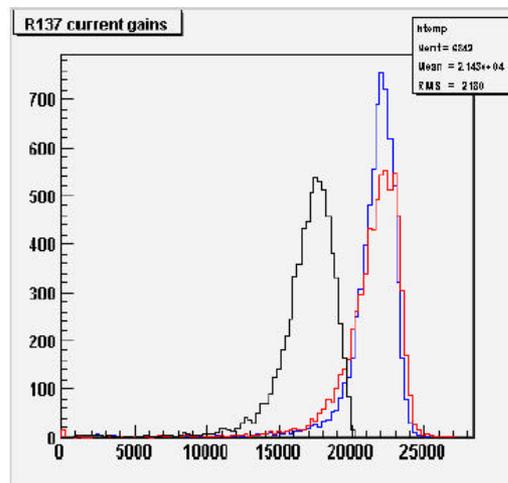
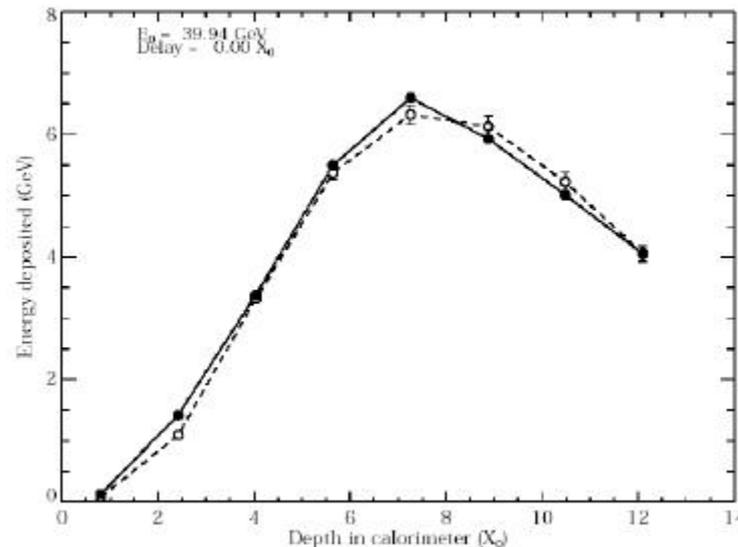
– Corrects for energy escaping out the back of the CAL

- Mean longitudinal profile of EM shower energy deposition is well-described by gamma distribution:

$$\frac{dE}{d(bt)} = E_0 \frac{(bt)^{a-1} e^{-bt}}{\Gamma(a)}$$

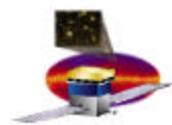
– Process:

- Measure energies deposited in slices through CAL
- Integrate profile model
- Find best fit for starting point and incident energy



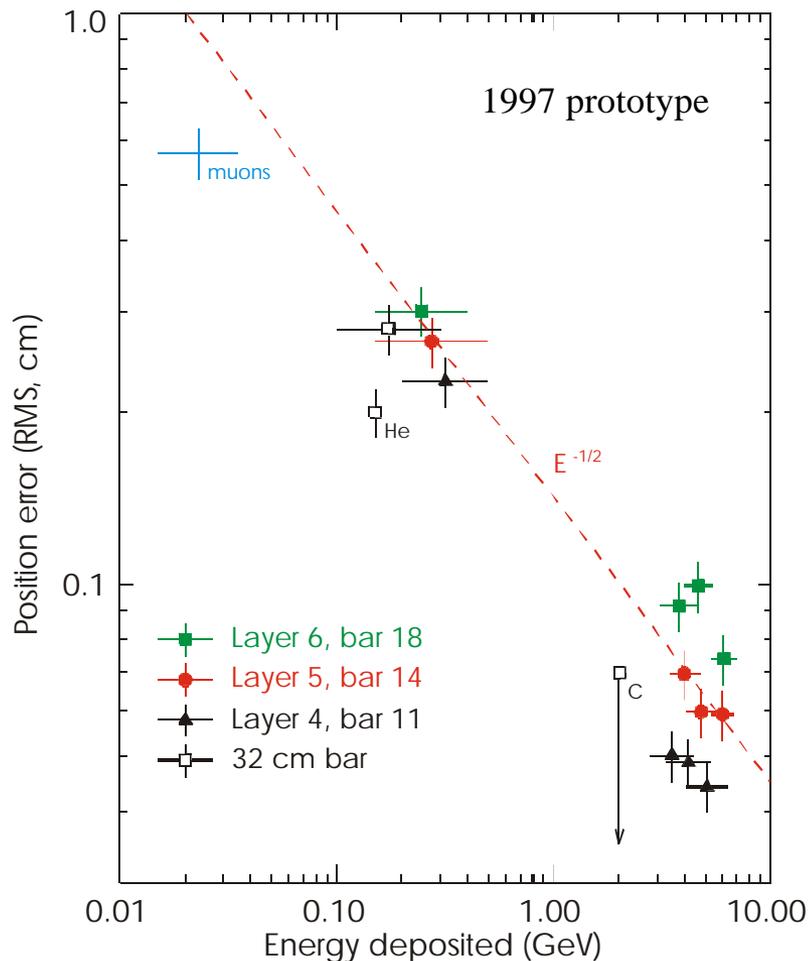
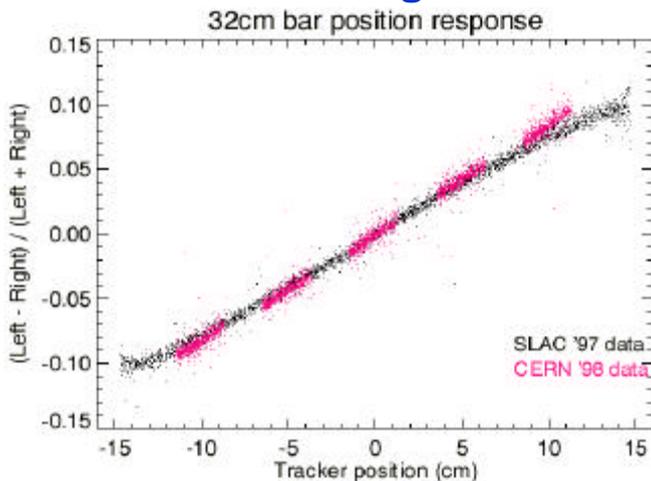
sum 7%
profile fitting 5.3%

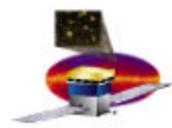




Shower Imaging in CsI

- Position reconstruction in xtal
 - Relies on position-dependence of CsI light output (“tapering”)
 - Achieved by roughening surface of CsI and reading out both ends
 - Position μ difference in signal
 - Difference = “light asymmetry”
 - Resolution is intrinsically precise
 - In practice, dominated by mapping uncertainty and electronic noise
 - 1997: Demonstrated position error of 10^{-3} of xtal length





Concept Implementation

□ Detectors

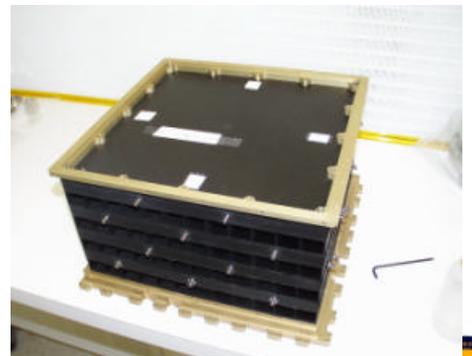
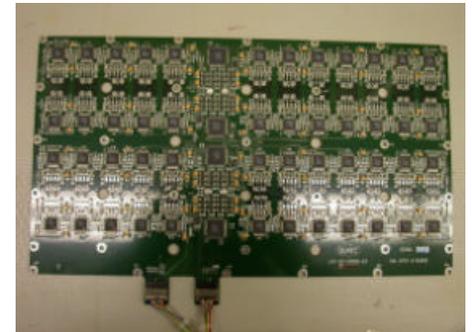
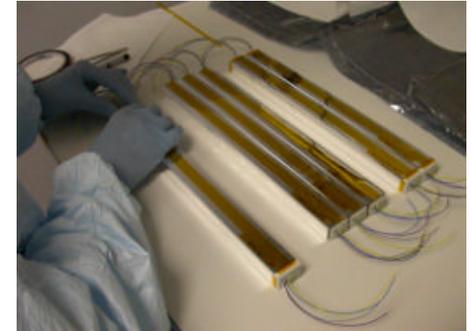
- Highly segmented
 - No individual packaging: reject NaI(Tl), use CsI(Tl)
 - CsI(Tl) read with photodiodes gives ~ same light yield as NaI(Tl)
- Photodiode readout
 - Small, lightweight, low power, rugged
 - Redundant readout gives fault protection and positions within each CsI xtal

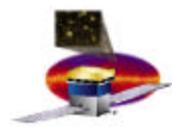
□ Electronics

- Large channel count requires low power per channel, ASICs
- Large dynamic range ($\sim 10^5$) is demanding
- Need to minimize space, passive/empty volumes

□ Mechanical

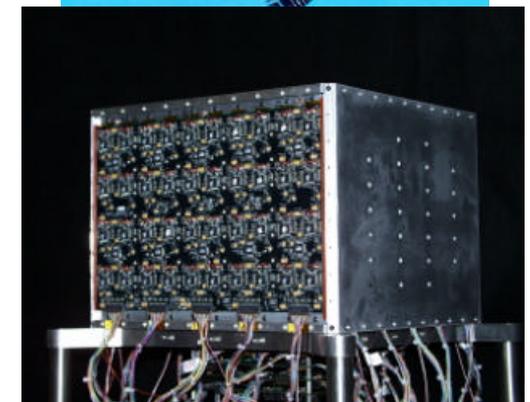
- Carbon structure gives stable dimensions and fixture of detectors over thermal range and against launch loads
- Supports detector readout on each side face of CAL





Design Evolution

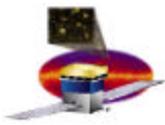
- ❑ Sampling calorimeter rejected
- ❑ Active CsI calorimeter
 - Initial concept
 - Vertical CsI bars, one PD per xtal
 - 1996 beam test prototype
 - Transverse CsI bars, two PDs per xtal
 - Demonstrated shower energy profiling
 - 1997 beam test prototype
 - Transverse CsI bars, hodoscopic layout
 - Demonstrated good longitudinal position resolution
 - Beam Test Engineering Model (BTEM)
 - Essentially full-size tower (10 xtals x 8 layers)
 - ASIC readout
 - SLAC beam test, GSI beam test, Balloon flight



BTEM

Naval Research Lab
Washington DC



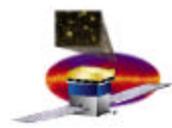


Testing History

□ Calorimeter Beam Tests

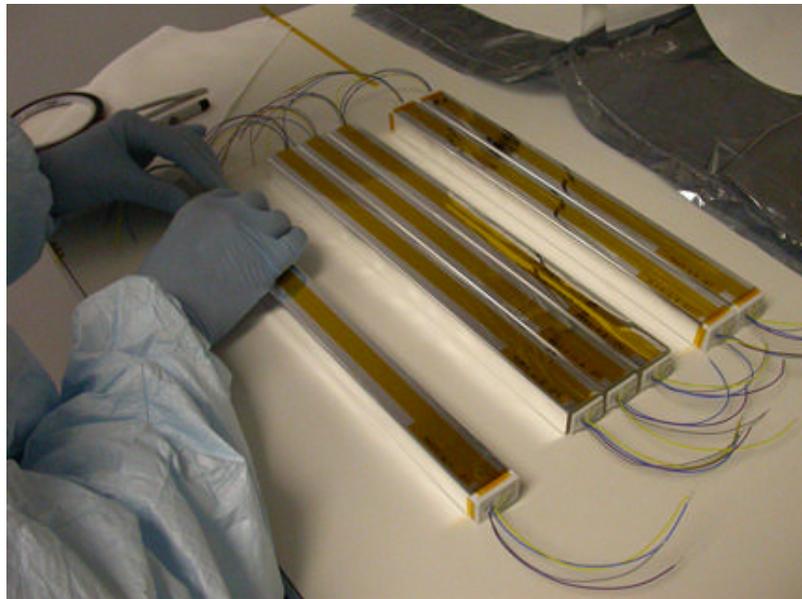
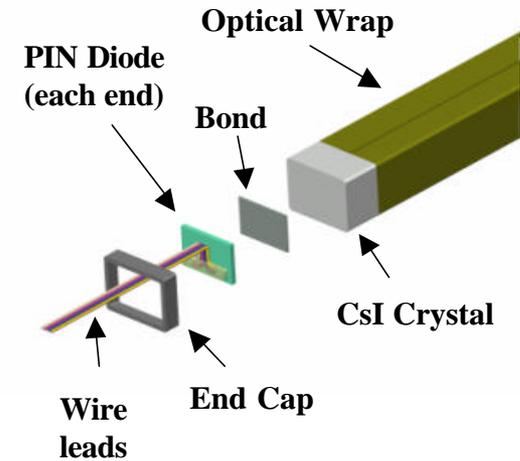
Test	Beams	Instrument	Proof of Concept
SLAC 1996	Photon and e	19-cm xtals on axis	CsI(Tl) with PD readout
SLAC 1997	Photon and e	Hodoscopic 19-cm xtals	Shower profiling Position reconstruction
MSU 1998	H, He, and C at 160 MeV/u	1997 CAL and 31-cm xtals	Crystal mapping with particles
CERN 1998	Photon and e	31-cm xtals	Crystal mapping
SLAC 1999	Photon, e, and p	BTEM calorimeter	Full-size Tower concept, DPD, ASICs
CERN 1999	Photon and e	31-cm xtals	High energy shower profiling
GSI 2000	C and Ni at 400- 700 MeV/u	BTEM and 37-cm xtals	Charged-particle identification





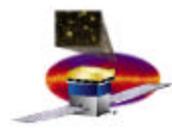
Crystal Detector Element

- ❑ Principle: CDE is a testable detector
- ❑ CDE has four components
 1. Active detector: CsI(Tl) crystal
 2. Readout: two photodiodes
 3. Optical seal: reflective wrapper
 4. Mechanical interface: two end caps



EM CDEs during wrapping and attachment of end caps





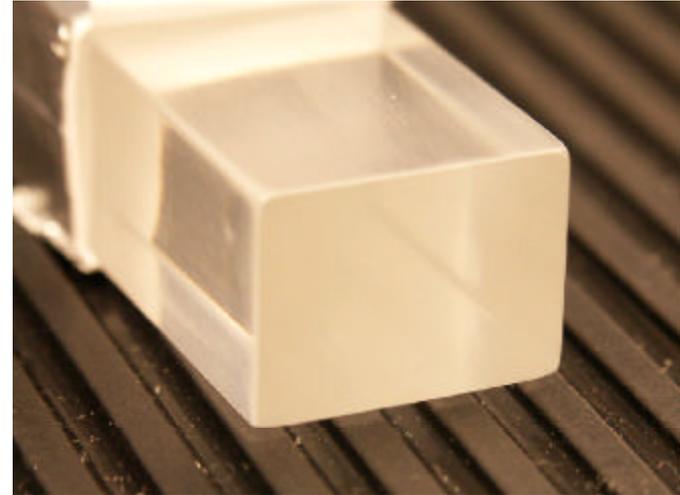
Crystals

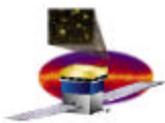
□ Principle

- High light output
- High stopping power
- Energy and position sensitive
- Low cost
- Compatible with mechanical concept

□ Implementation

- Csl(Tl) crystals
 - Choice of vendors
 - Crismatec (France)
 - Amcrys H (Ukraine)
 - » Identical performance from Amcrys at much lower cost
- Light tapering
 - Xtal surfaces treated to attenuate light





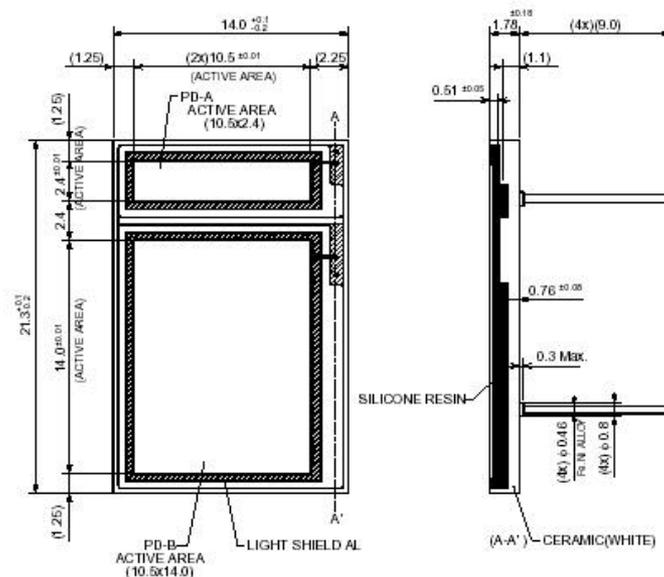
Photodiodes

□ Principle

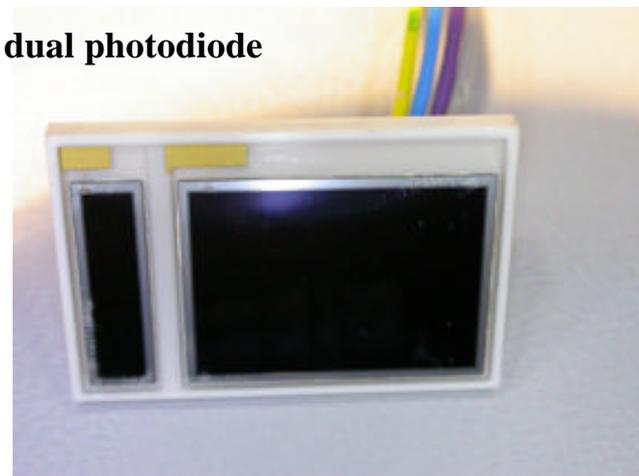
- Good spectral response match to CsI(Tl) scintillation
- Very small mass, volume, and power
- Rugged
- Commercial product with space heritage

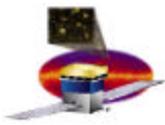
□ Implementation

- PIN photodiodes
- Two diodes to help cover dynamic range
 - Both diodes large enough for ground testing (muons)
- Single carrier for easier mounting
- Need flexible interconnect to AFEE



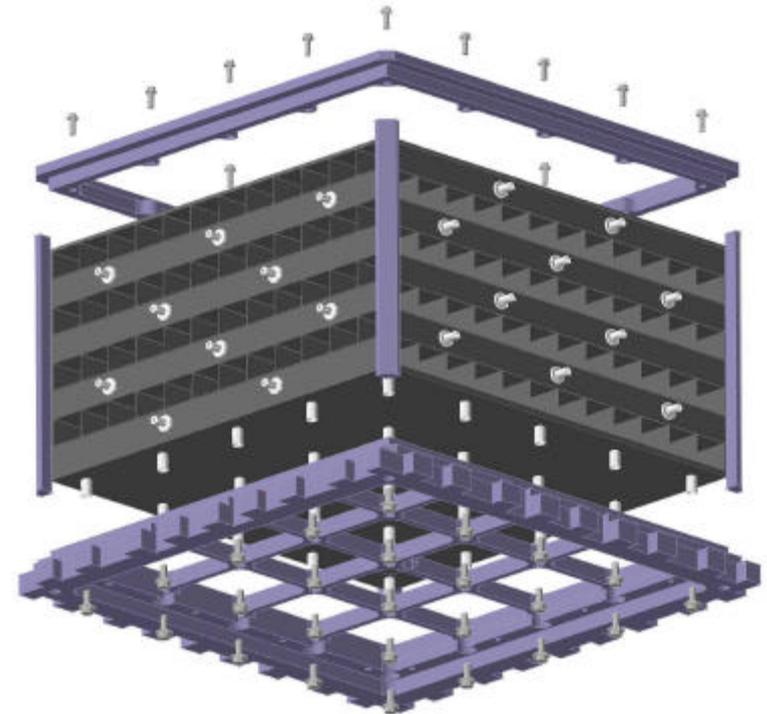
EM dual photodiode



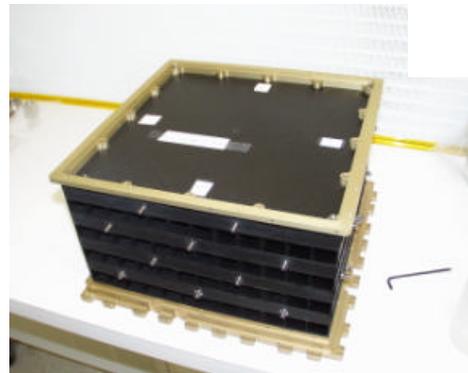


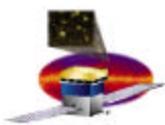
Mechanical Structure

- Principle: Stable mechanical structure to define CDE locations and secure them against launch loads
 - Must hold ~80 kg against ~6 g with ~10 kg
 - Must account for thermal expansion of Csl
- Implementation:
 - Carbon composite structure
 - 96 individual cells
 - Al top, bottom and side plate
 - Bottom plate provides attachment to Grid, and support for TEM and Power Supply
 - Sides provide support for AFEE boards



EM Structure





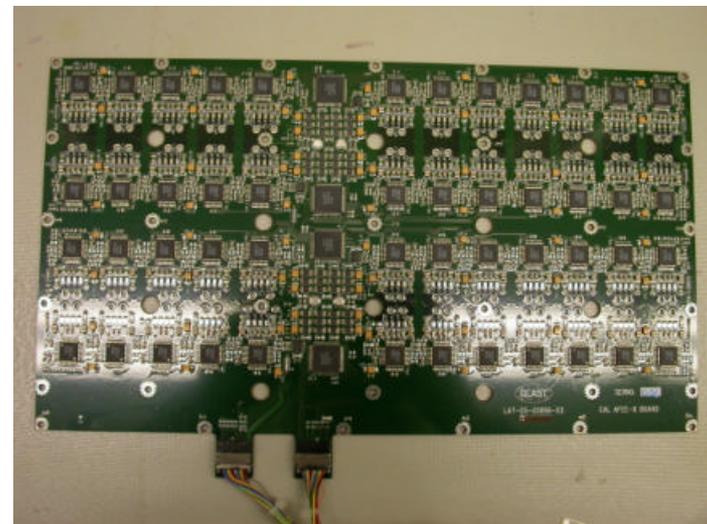
Electronics

□ Principle

- Need to cover a very large dynamic range (few $\times 10^5$)
- Low noise (~2000 electrons noise)
- Low power (~20 mW per crystal end)
- Limited space (8 mm thickness), match pitch of CsI crystals (28x40 mm)
- Interface to TEM

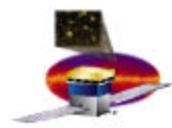
□ Implementation

- Use 1 custom analog and 1 custom digital ASIC to minimize power
- Use 2 input signals to reduce dynamic range requirement on electronics
 - Each input signal goes into 2 gain ranges
 - Have ranges to 200 MeV, 1.6 GeV, 12.5 GeV and 100 GeV
- Use commercial 12-bit ADCs
- Separate analog from digital on front-end (“AFEE”) board
- Low dead time (20 ms)
- Sparsify data (zero suppress)



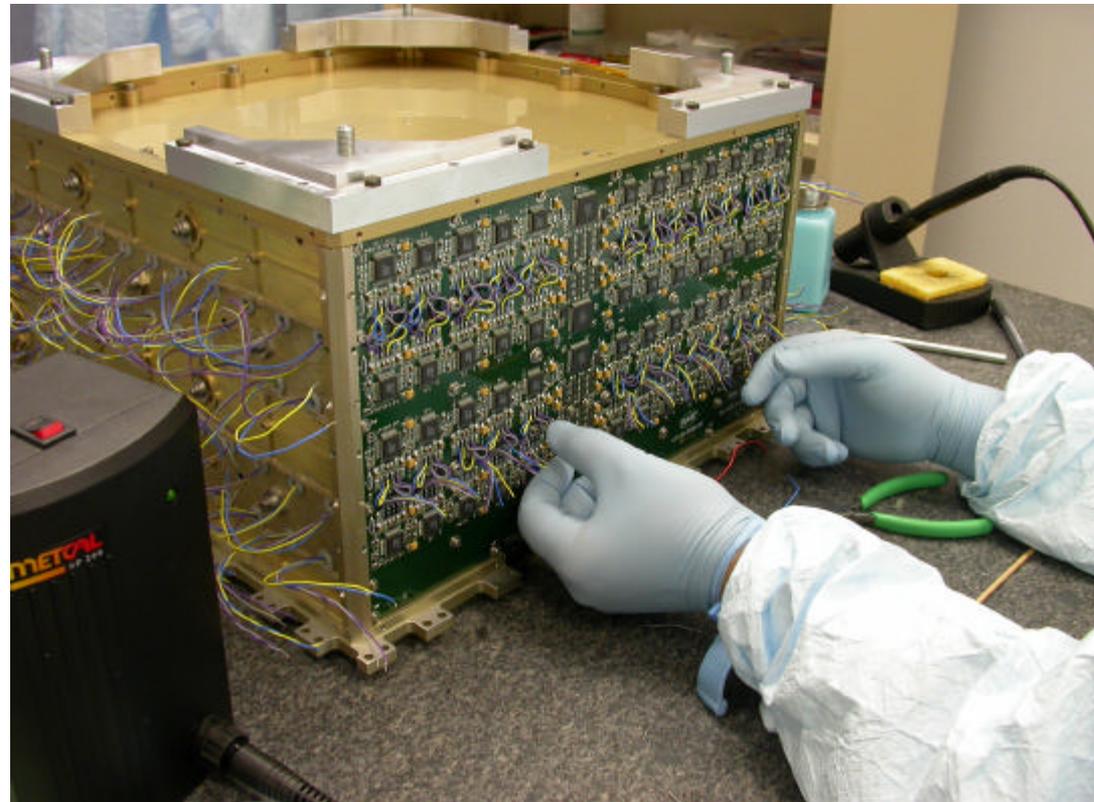
EM AFEE board

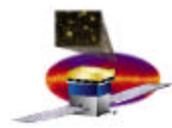




Engineering Model

- EM Calorimeter
 - Full-size calorimeter
 - Fully populated with CDEs and AFEEs

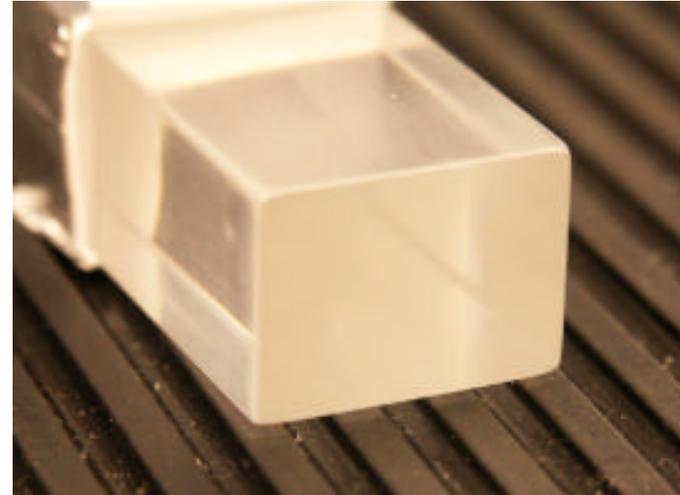


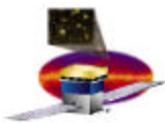


EM Crystal Performance

- **Csl(Tl) crystals**
 - Vendor: Amcryst H
 - Procured 244 crystals
 - Dimensional specs changed after purchase, so we committed two sins
 1. Remachined length
 2. Remachined chamfers
 - Amcryst would not guarantee optical performance after this extensive handling, so we waived light taper requirement for EM

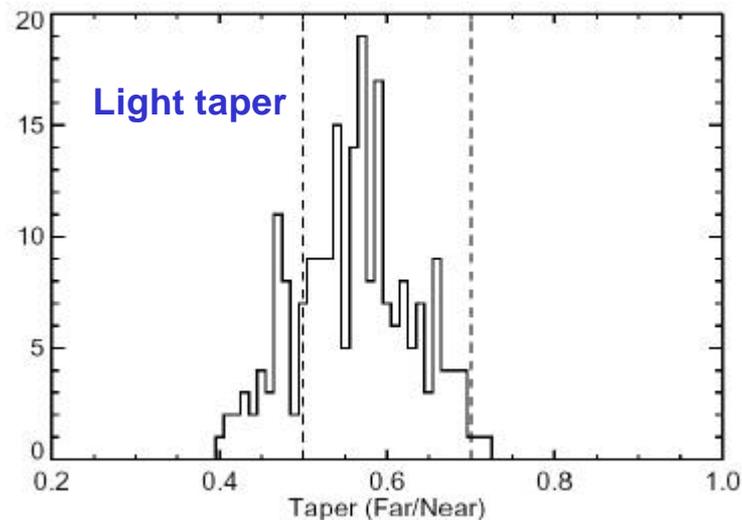
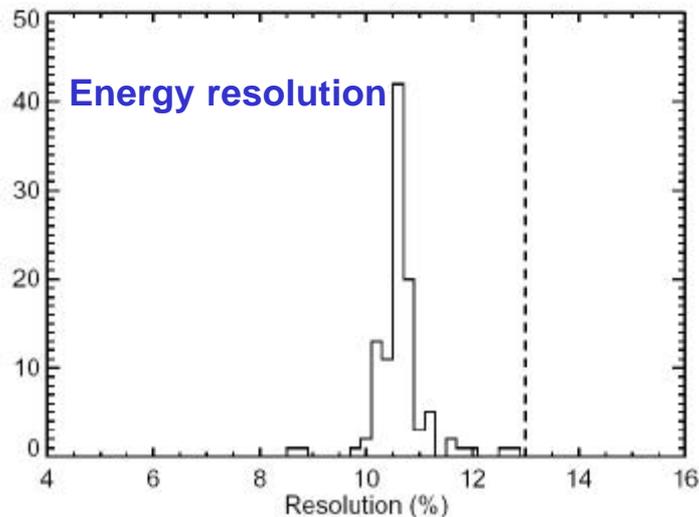
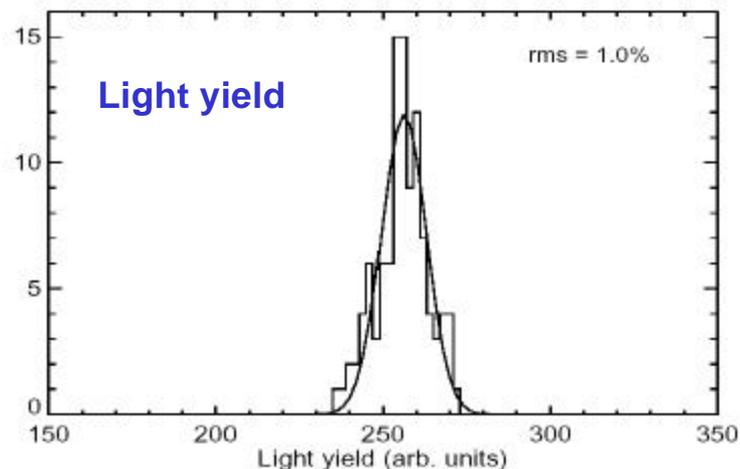
- **Testing**
 - Visual inspections performed at NRL
 - Xtal dimensions were verified at Kalmar
 - Optical performance was tested at Kalmar and NRL
 - Xtal Optical Testing Station (XOTS)

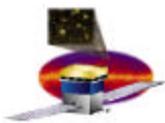




EM Crystal Optical Performance

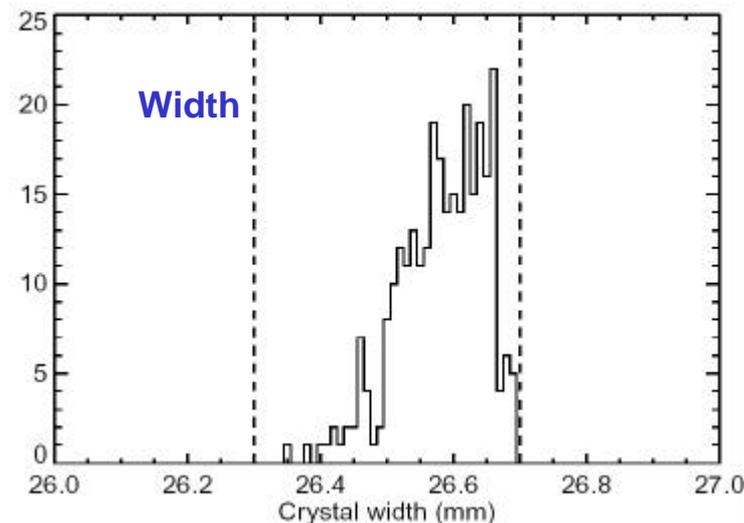
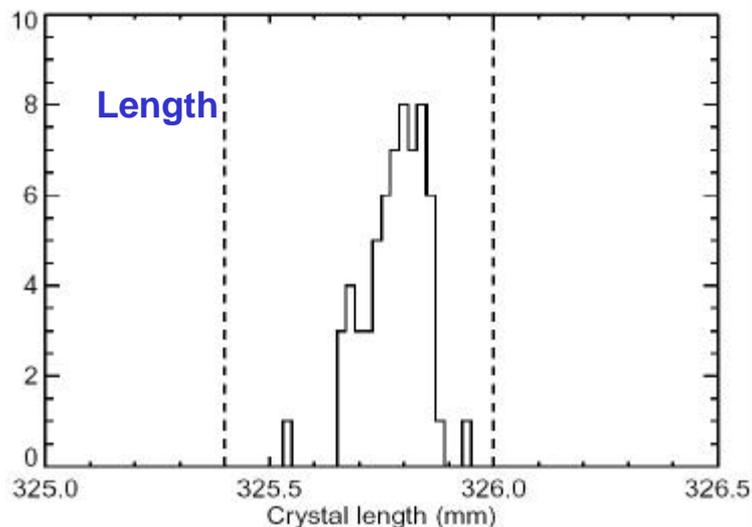
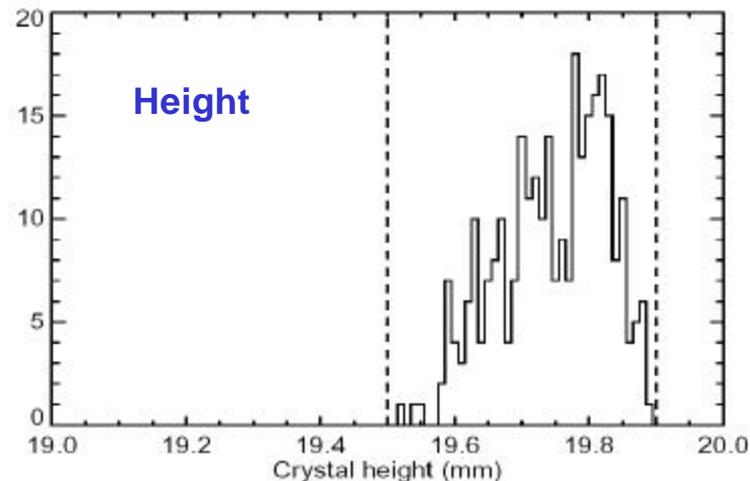
- Results of EM performance testing with Xtal Optical Test Station
 - Light yield constancy is within spec
 - Light taper is (mostly) within spec
 - One batch was below spec, likely caused by remachining of xtals
 - We waived EM taper requirement
 - Energy resolution is within spec

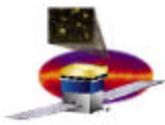




EM Crystal Dimensions

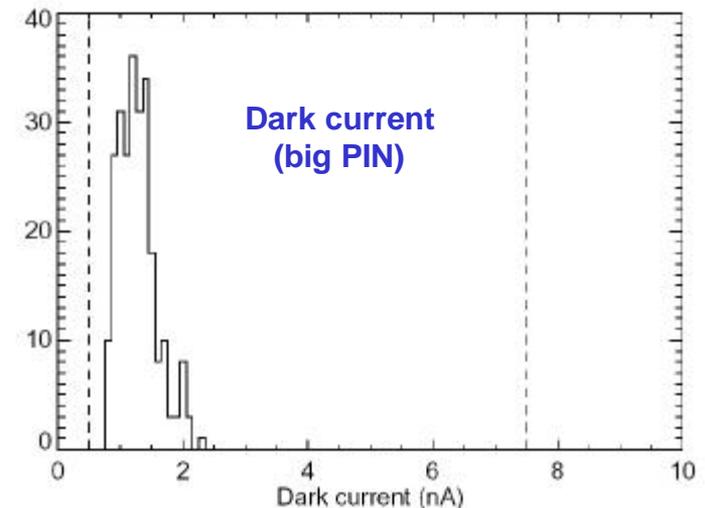
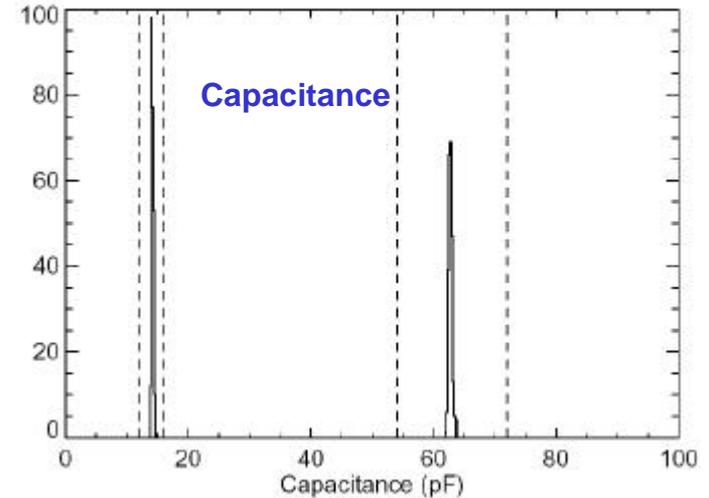
- Dimensions of EM crystals
 - Length, width, and height are **within spec**
 - Note obvious truncating of width distribution
 - Optical surface treatment is applied to width
 - Xtals needed less surface treatment than Amcrysts expected

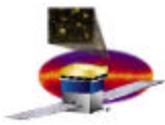




EM Photodiode Performance

- EM photodiode
 - Vendor: Hamamatsu, custom S8576
 - Procured 650 DPDs according to spec LAT-DS-0072-03
- Testing
 - Electrical performance at NRL and in France
 - Within spec
 - Optical performance in France
 - Within spec
 - Radiation hardness in France
 - Within spec
 - Bonding studies at NRL and in France
 - Within spec
 - Thermal stability at NRL and in France
 - Fail (see DPD, section 5.1), so optical window material will change





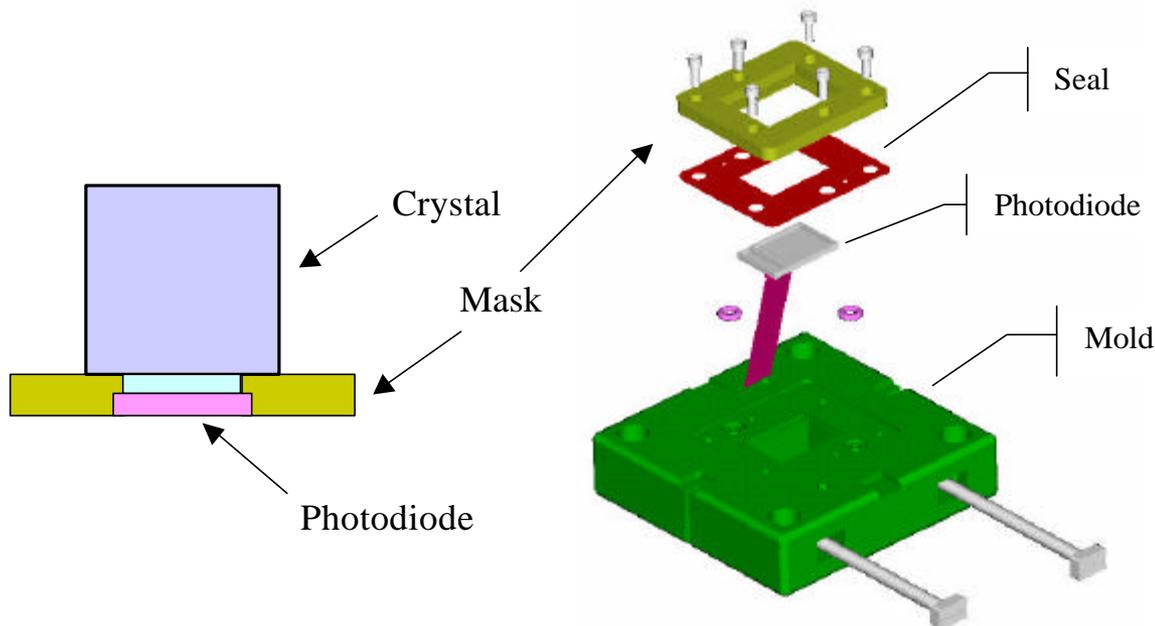
Issue at PDR: Diode Bonding

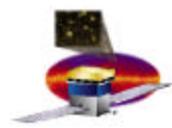
- Need an optical bond between photodiode and CsI
 1. Must be optically clear
 2. Must adhere to CsI
 3. Must be stable against thermal cycling
 - **Items 2 & 3 were a problem**
 - **CsI behaves like “oiled lead”**
 - Not all adhesives adhere to it
 - **Mismatch between large coef of thermal expansion (CTE) of CsI and small CTE of PD**
 - Hard epoxies used in BTEM failed optically
 - Optical waxes used in earlier prototypes would liquify
 - **Extensive research program in US and France**
 - **Soft epoxies, silicones, bonding surface treatments, ...**
 - **Solution: silicone encapsulant with compatible primer**
 - Dow Corning DC93-500 with DC92-023
 - Developed bonding process, implemented on EM CAL



EM Diode Bonding Process

- Bonding process for EM developed together with Swales Aerospace
 - Teflon mask defines bond thickness and area, and locates diode precisely on xtal end face
 - Mold assembly allows diode and xtal faces to be primed prior to bonding
 - Bond material is injected into defined volume and allowed to cure





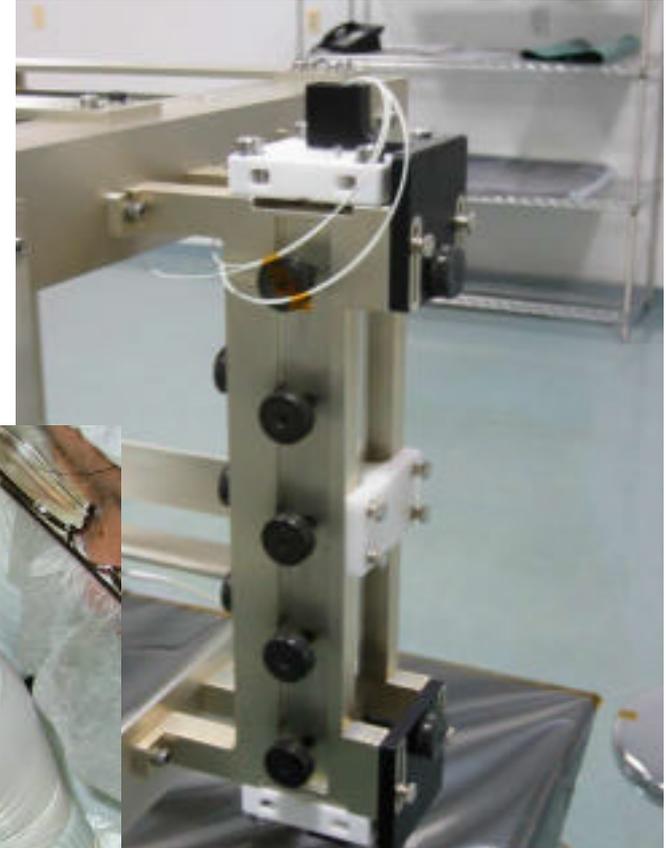
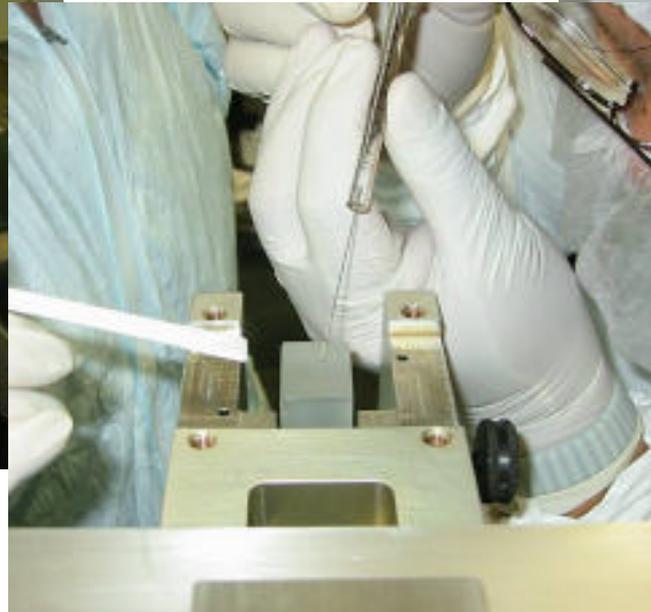
EM Bonding Process

**EM build:
110 CDEs at Swales
14 CDEs at Saclay**



Hanging xtal in bonding fixture

Priming xtal



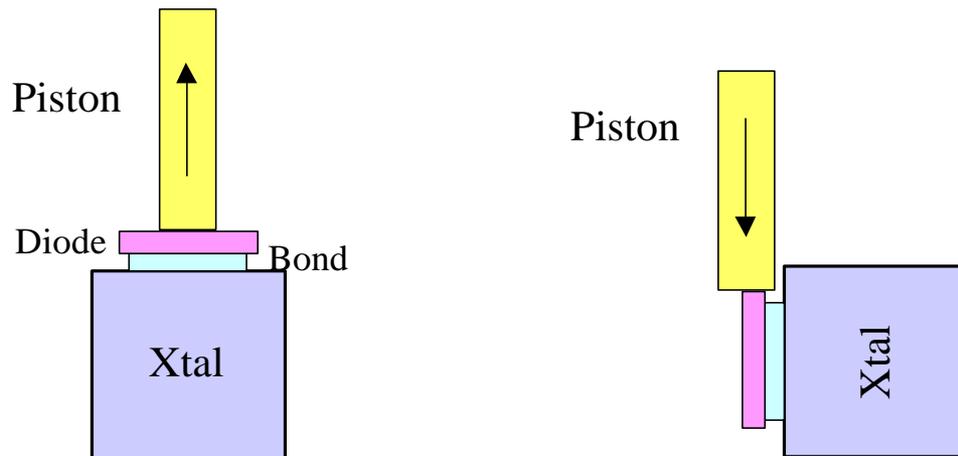
Silicone injected, waiting to cure

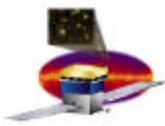


EM Bond: Mechanical Strength Tests

- ❑ Two types of destructive tests were performed at NRL
 - Tensile strength requirement
 - 10 N (2.2 lbf)
 - Shear strength requirement
 - 0.12 N/mm² (8 lbf = 35 N for EM diode)

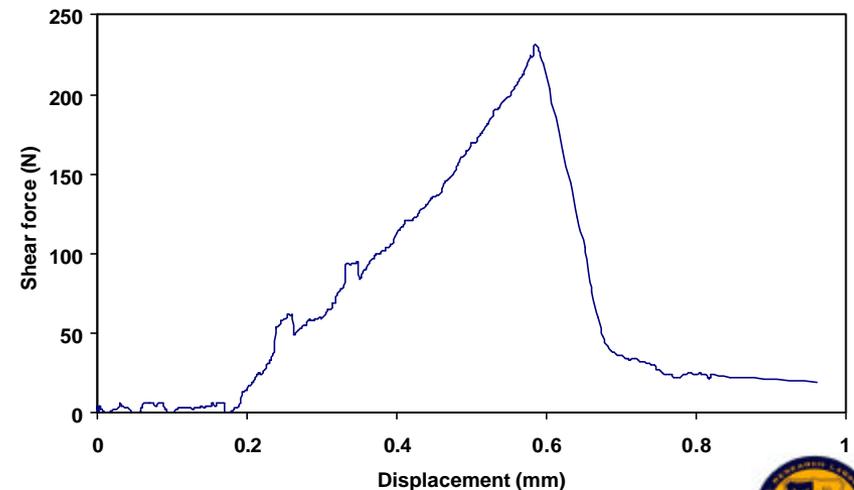
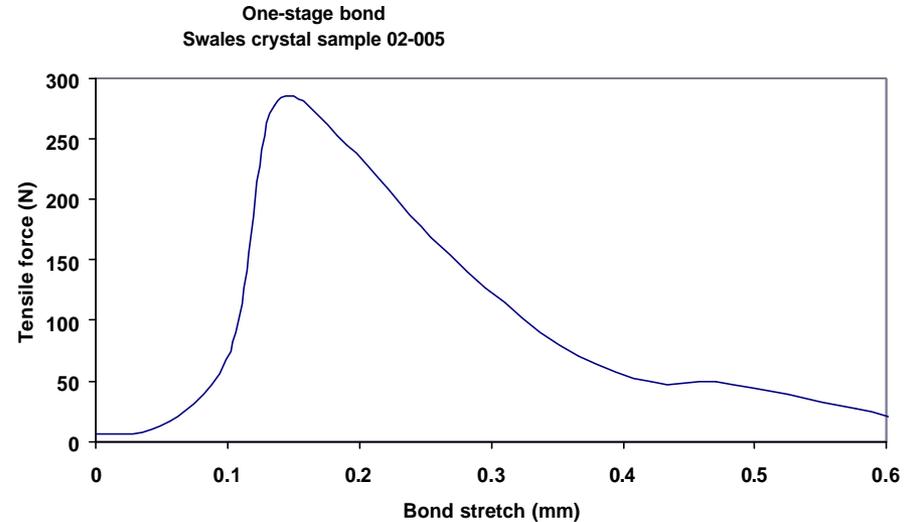
- ❑ Samples are pulled or sheared to failure in Dynamic Load Test Stand

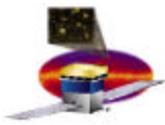




EM Bond: Strength Tests

- More than 65 bonds tested
 - Tensile strength sample
 - Fails at ~280 N
 - 28 x requirement
 - Shear strength sample
 - Fails at ~230 N
 - 7 x requirement
- Typical failures are
 - ~10 x strength requirement
 - At interfaces, rather than in bond material
 - Slightly more likely at diode face
- Adhesion problem with CsI is solved





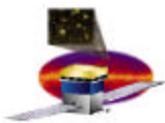
EM CDE Performance

- ❑ EM CDE build
 - 110 at Swales Aerospace
 - 14 at Saclay
- ❑ Verifying EM CDE performance
 - Mechanical
 - Do they fit in Mech Structure?
 - Optical
 - Muon telescope
 - Two layers of xtals
 - » Top layer is EM CDEs
 - » Bottom layer is prototype 37-cm xtals
 - Lab electronics and DAQ
 - Image muons passing through array
 - Tested all EM CDEs



Saclay and Swales CDEs have identical performance





EM CDE Optical Performance

□ Performance of EM CDEs

– Light yield

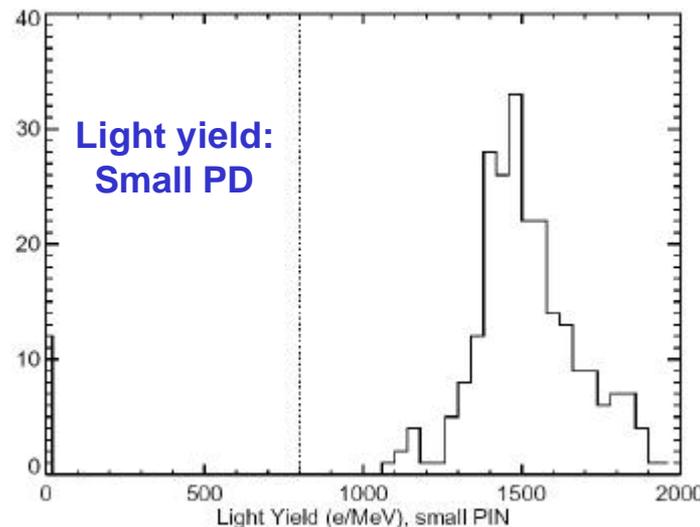
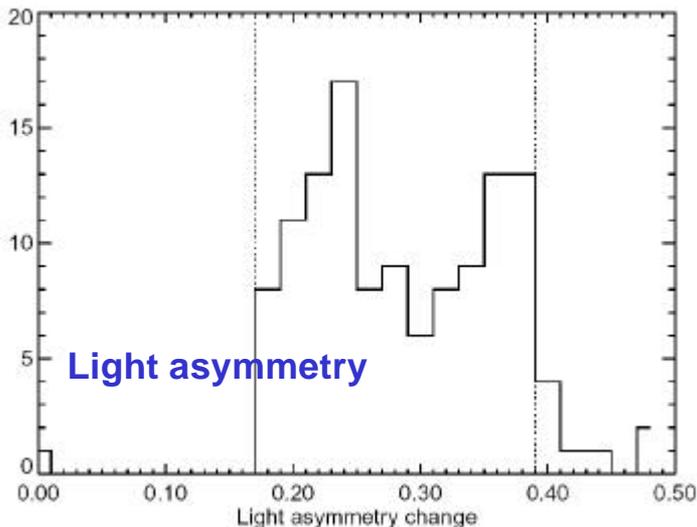
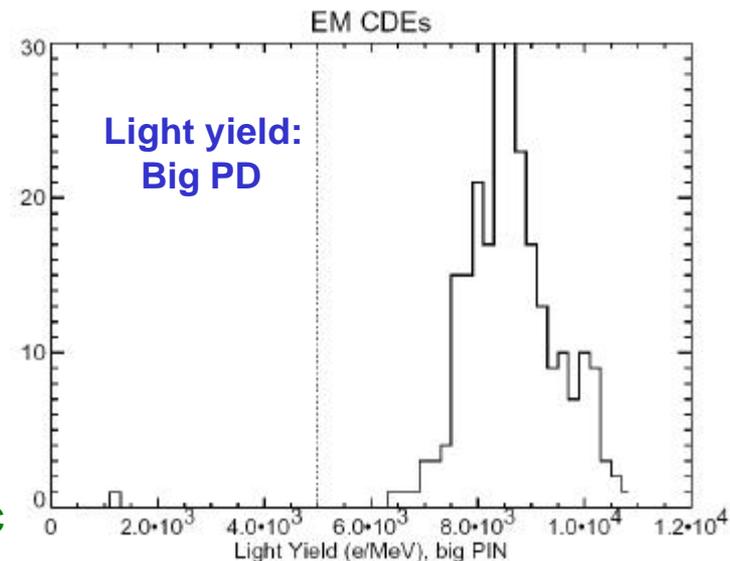
- **Big PD within spec**
 - Typical: 8000 e/MeV
 - EM Spec: >5000 e/MeV

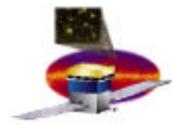
• **Small PD within spec**

- Typical: 1500 e/MeV
- EM Spec: >800 e/MeV

– Light asymmetry (mostly) within spec

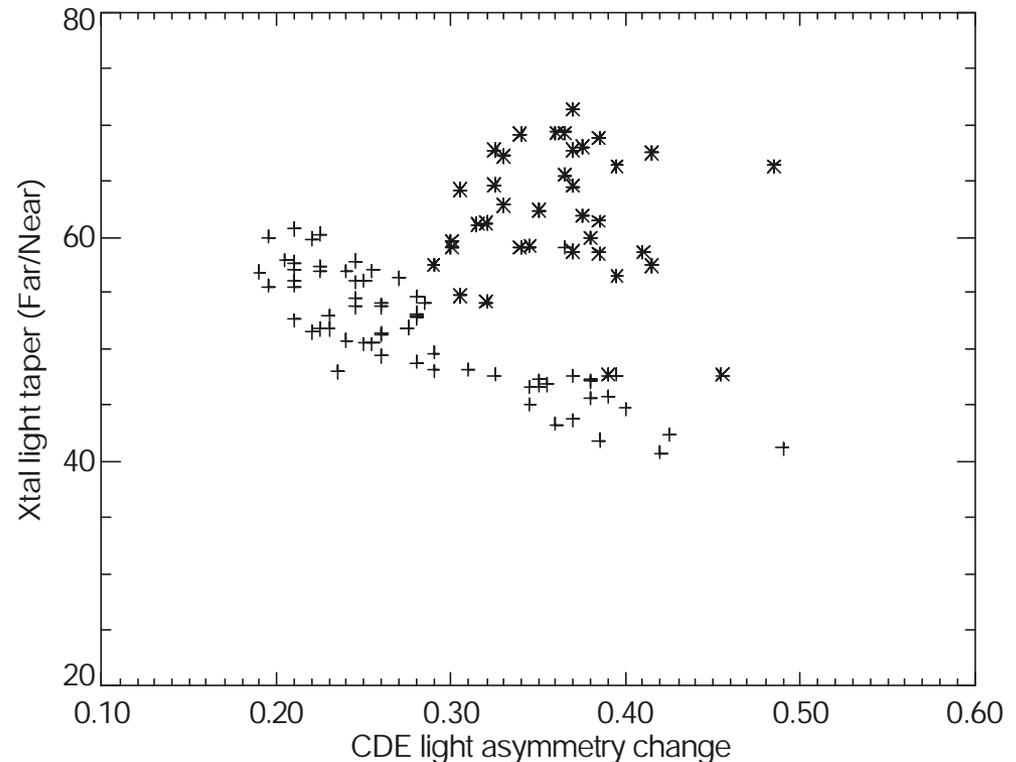
- EM spec: >0.17, <0.39

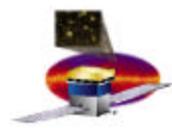




EM CDE Testing

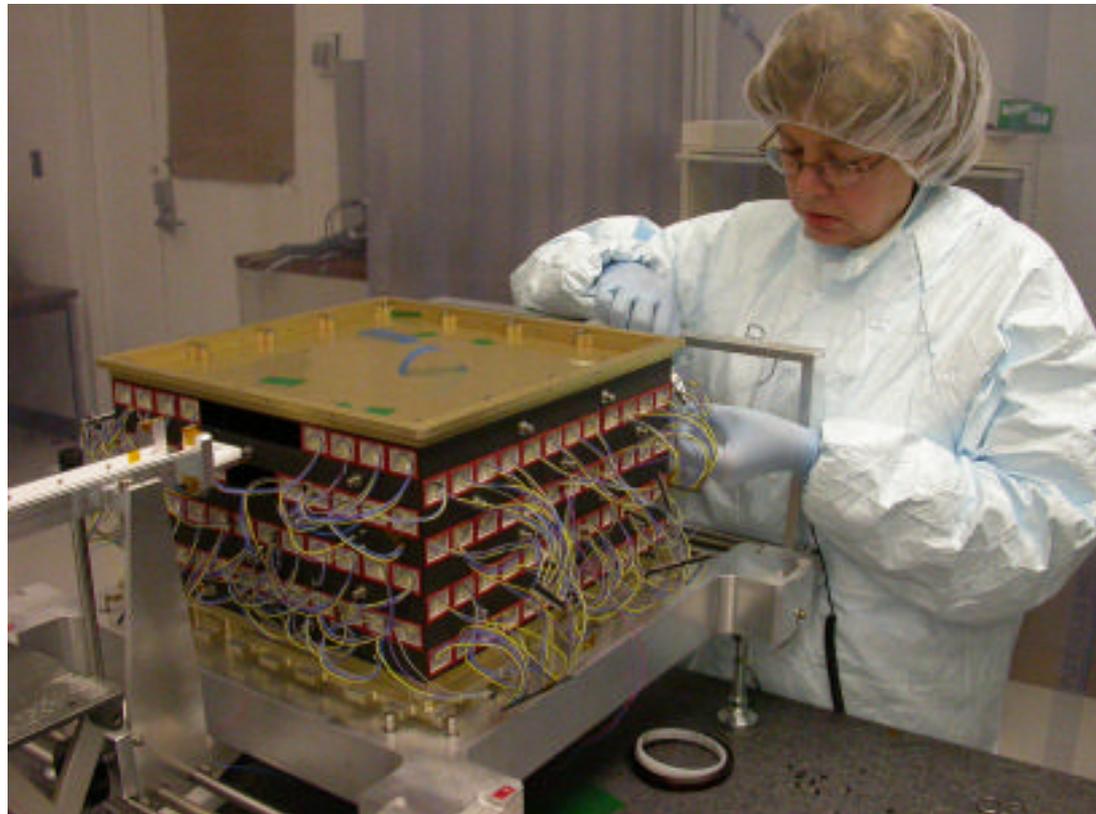
- **Comparison of xtal to completed CDE**
 - **As expected, xtal light taper is strongly correlated with CDE light asymmetry**
 - **Xtals retapered at NRL (star symbol) are not correlated, also as expected**
 - **CDE performance is within spec**
 - **Conclusion: CDE manufacture preserves xtal optical properties**

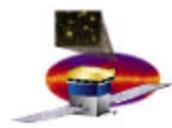




EM PEM Assembly

- ❑ EM Pre-Electronics Module
 - 82 Swales CDEs and 14 Saclay CDEs successfully inserted into Mechanical Structure

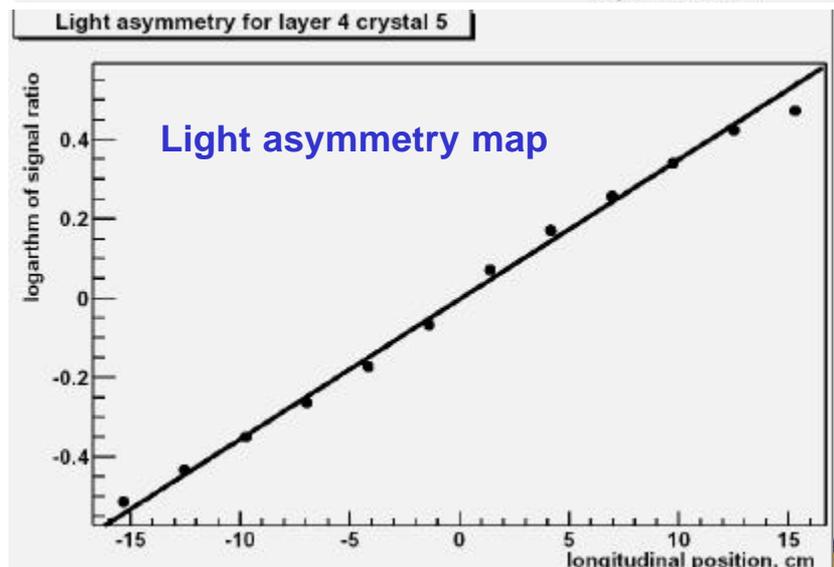
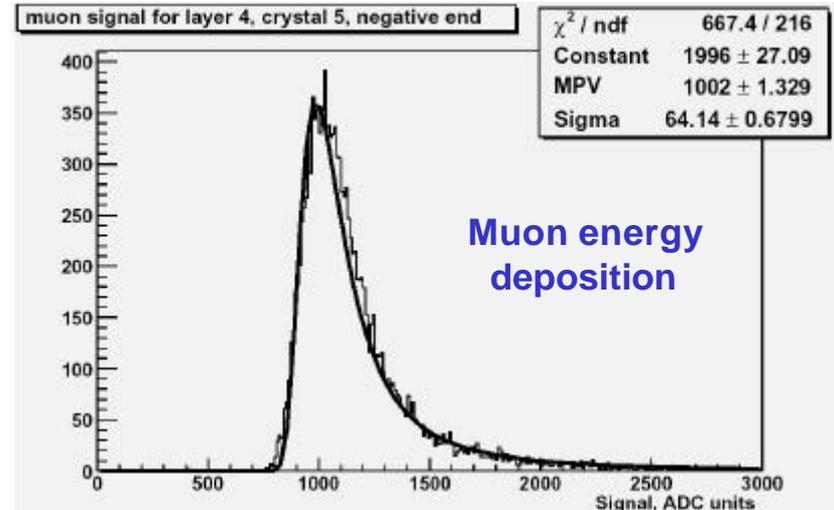
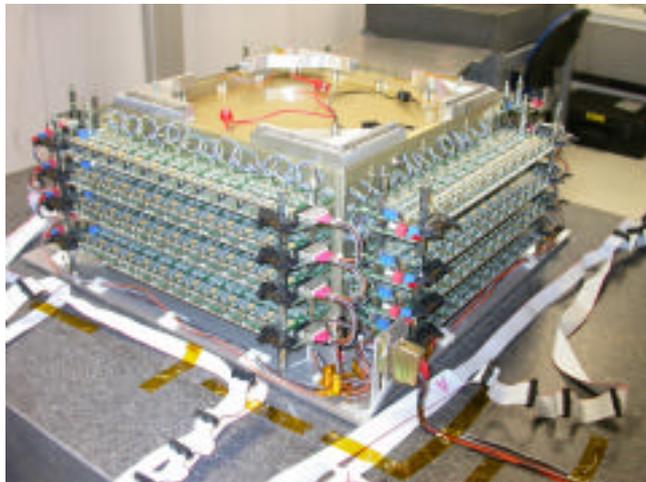


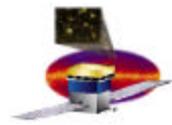


EM Pre-Electronics Module Performance

Performance of EM PEM

- Assembled PEM with GSE Checkout electronics
- >5 million muons collected
- Data being analyzed with Ground Science Analysis Software system
 - Muon trajectories imaged
 - CDE light tapers mapped

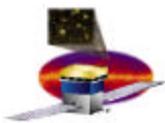




Calibration

- ❑ How will we know Flight CAL achieves science requirements?
- ❑ How do we calibrate the instrument?
- ❑ What needs to be calibrated?
 - Energy measurement
 - Need relative calib among xtals and absolute calib
 - Level III requirements: 3% relative, 10% absolute
 - Position measurement
 - Need calibration of light taper in each xtal
 - Level IV requirement: taper slope uncertainty of 10%
 - Calibration data sources
 - Pre-launch
 - Electronic calibrations
 - Sea-level muons
 - Beam tests of CU (4-module array)
 - On-orbit
 - Electronic calibrations
 - Cosmic rays





Calibration

□ Electronic calibration

- Inject known charge into each Front End

- Measures

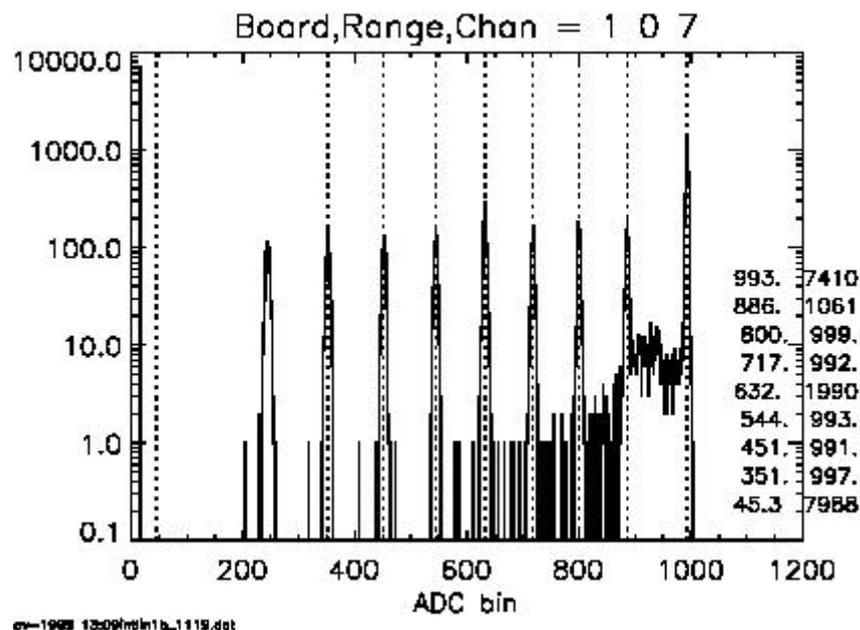
- Electronic gain (e/bin)
- Integral non-linearity

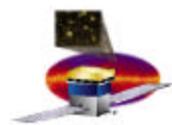
- Does not measure “optical gain”

- i.e. conversion between energy deposited and electrons at each Front End

- Automated process can be run on ground or in flight

- Ramps charge through full dynamic range
- Returns histogram or centroid of each input

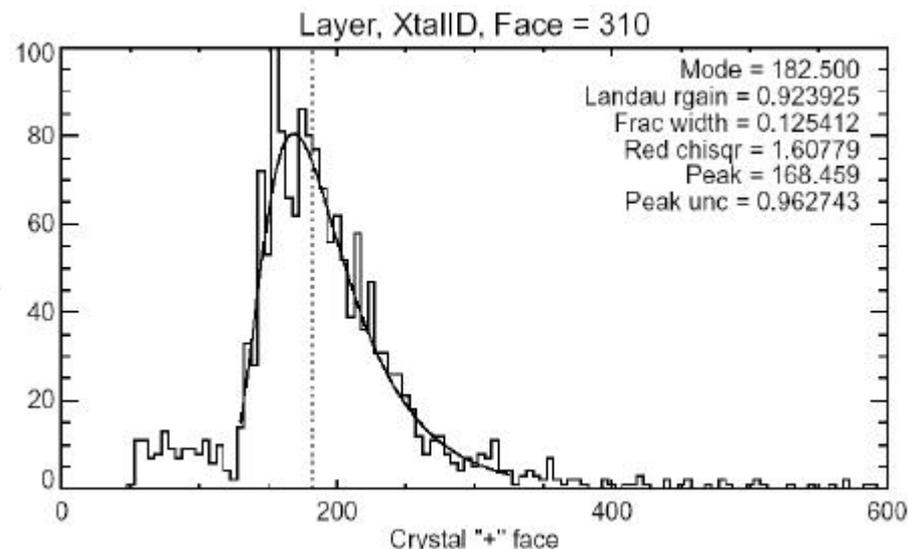


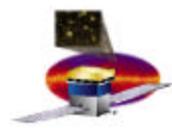


Calibration

□ Sea-level muon calibrations

- Performed only on ground
 - At CDE level, PEM level, and Module level
- Image muons passing through detectors
 - Muon DE ~ 11 MeV per xtal, only $\sim 10^{-4}$ of FE dynamic range
 - Measures
 - Optical gain, i.e. energy per bin
 - Light taper
 - Does not measure full dynamic range
- Requires hodoscope
 - CDE testing in France
 - External muon telescope
 - PEM and Module testing in US
 - CAL xtal hodoscope
 - TKR, when available

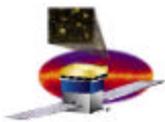




Calibration

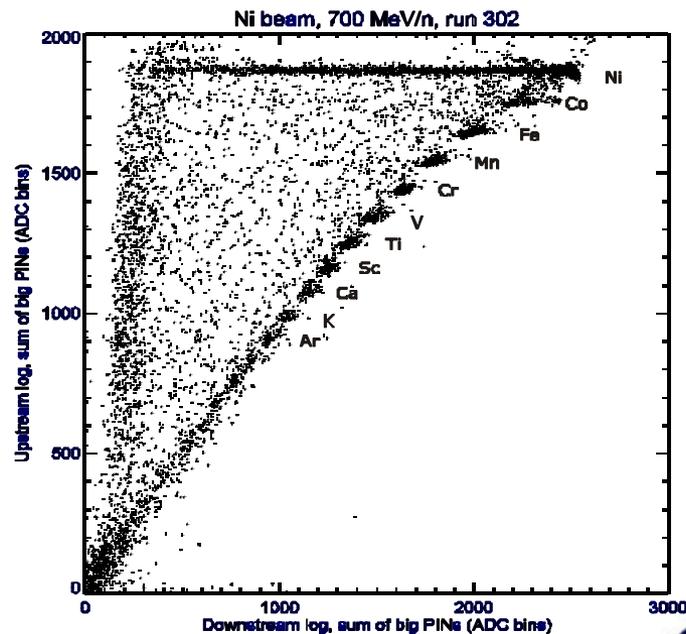
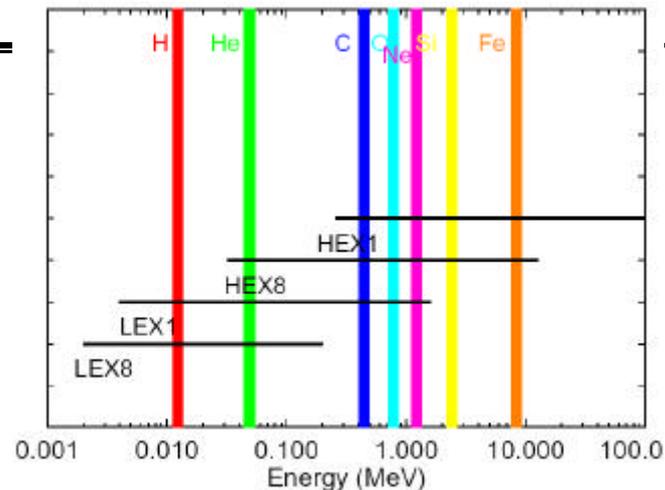
- ❑ **Beam tests**
- ❑ **Engineering Model**
 - **Scheduled for Nov 03 at GSI (Darmstadt, Germany)**
 - **Heavy ion beams**
 - **Measures**
 - Energy scale
 - Scintillation efficiency for cosmic rays
- ❑ **Calibration Unit (CU = first 4 CAL+TKR Modules)**
 - **To be performed at SLAC, Summer 04**
 - **Photon, electron, hadron beams**
 - **Measures**
 - Optical gain
 - Light taper
 - Energy scale
 - **Does not measure**
 - Scintillation efficiency

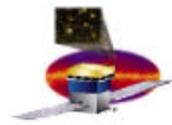




Calibration

- **Cosmic ray calibration**
 - Primary energy and position calibration of CAL
 - Performed only on orbit with full LAT instrument
 - High flux of GCRs gives good calibration of most of dynamic range
 - Measures
 - Optical gain
 - Light taper
 - Energy scale
 - Does not measure
 - Scintillation efficiency





Conclusions

- ❑ **Physical principles of design are well demonstrated**
- ❑ **Expect Flight Model to meet Level III requirements**
- ❑ **Engineering Model tests to date show performance (mostly) within spec**
- ❑ **Methods to determine and calibrate Flight Model performance are understood**

